

HMC788A Die Revision, Assembly Site, Marking and Material Change

HMC788A Qualification Results Summary

QUALIFICATION PLAN / STATUS			
TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3x25	Pass
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1x77	Pass
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3x25	Pass
Electrostatic Discharge <i>Human Body Model</i>	ESDA/JEDEC <i>JS-001</i>	3/voltage	Pass <u>±</u>250V
Electrostatic Discharge <i>Field-Induced Charged Device Model</i>	JEDEC <i>JESD22-C101</i>	3/voltage	Pass <u>±</u>1000V

* These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test.

Level 3 preconditioning consists of the following: Bake: 24 hrs @ 125°C, Unbiased Soak: 192 hrs @ 30°C, 60%RH, Reflow: 3 passes through an oven with a peak temperature of 260°C.